

Electronic Patent Application Fee Transmittal

Application Number:	10593152			
Filing Date:	18-Sep-2006			
Title of Invention:	ELECTRODEPOSITED COPPER FOIL WITH CARRIER FOIL ON WHICH A RESIN LAYER FOR FORMING INSULATING LAYER IS FORMED, COPPER-CLAD LAMINATE, PRINTED WIRING BOARD, METHOD FOR MANUFACTURING MULTILAYER COPPER-CLAD LAMINATE, AND METHOD FOR MANUFACTURING PRINTED WIRING BOARD			
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Filer:	Arnold Turk/Sean Shoolbraid			
Attorney Docket Number:	3209-124			
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Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
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